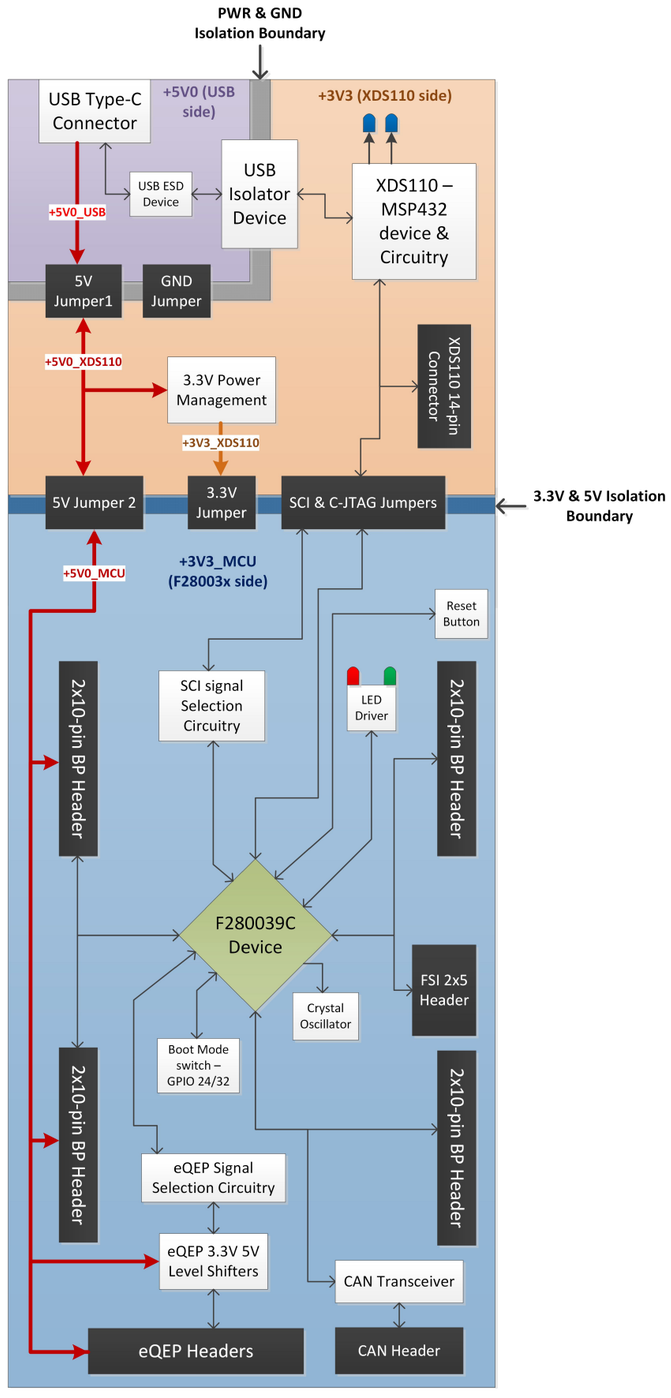

Orderable: LAUNCHXL-F280039C		Designed for: Public Release	Mod. Date: 10/8/2021
TID #: N/A		Project Title: LAUNCHXL-F280039C	
Number: MCU103	Rev: A	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 1 of 8
Drawn By:		File: MCU103A_Block_Diagram.SchDoc	Size: B
Engineer: Kevin Allen		Contact: http://www.ti.com/support	

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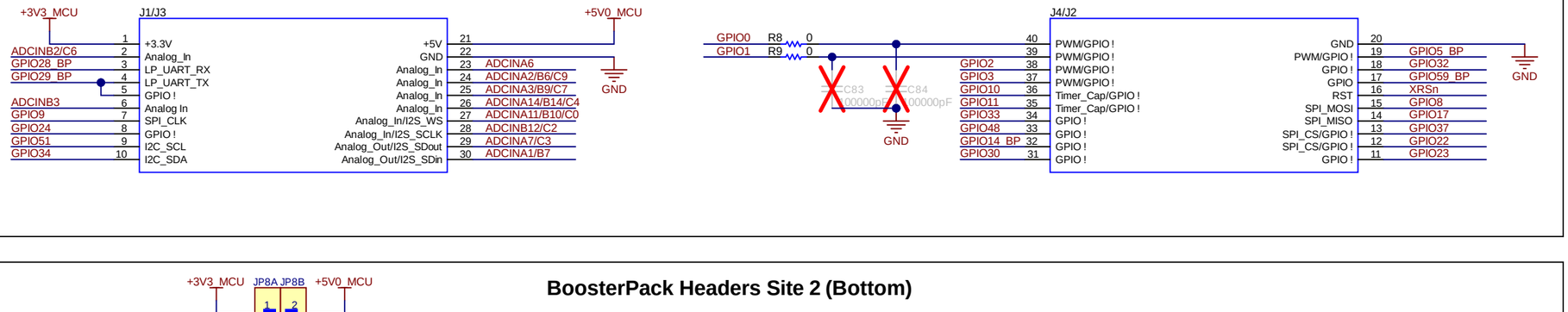
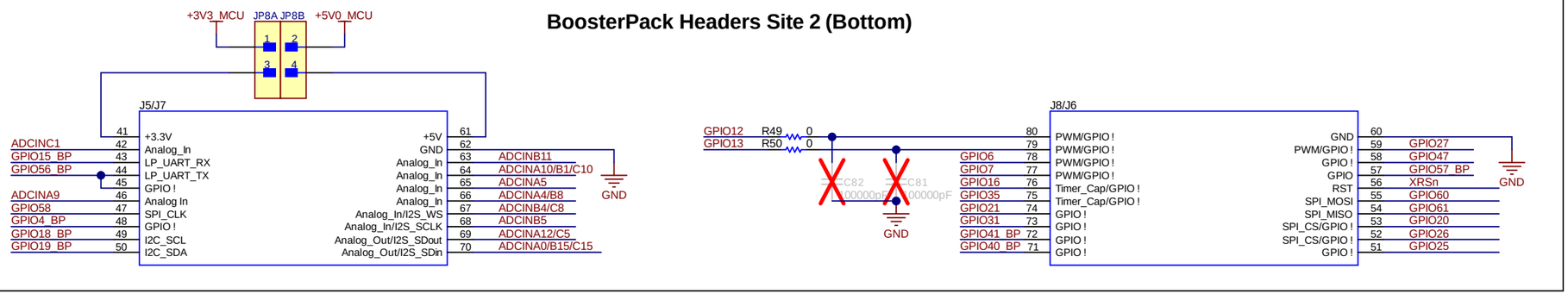
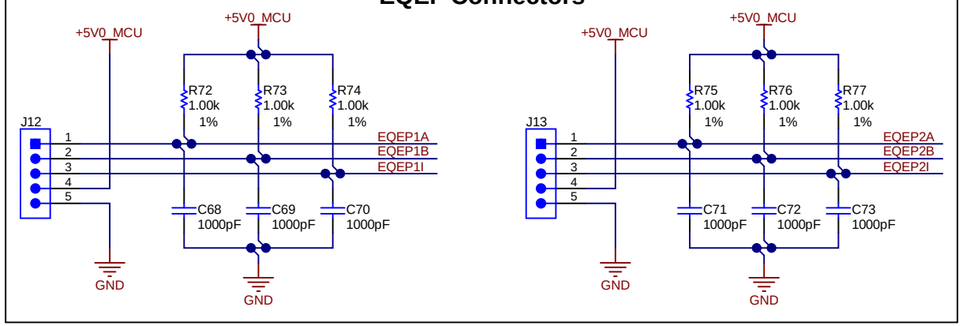
BoosterPack Headers Site 1 (Top)



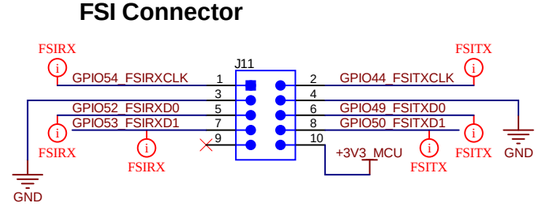
BoosterPack Headers Site 2 (Bottom)



EQEP Connectors

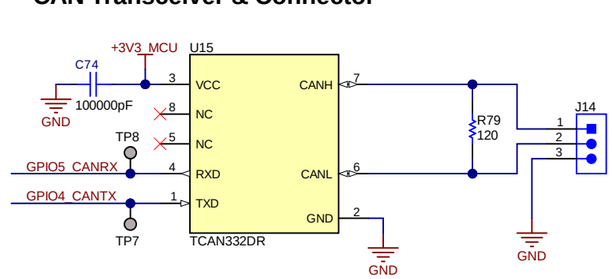


FSI Connector



FSIRXCLK, FSIRXD0, and FSIRXD1 length matched to each other with 25mil tolerance.
FSITXCLK, FSITXD0, and FSITXD1 length matched to each other with 25mil tolerance.

CAN Transceiver & Connector



Orderable: LAUNCHXL-F280039C		Designed for: Public Release	Mod. Date: 12/9/2021
TID #: N/A		Project Title: LAUNCHXL-F280039C	
Number: MCU103	Rev: A	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 2 of 8
Drawn By:		File: MCU103A_Connectors.SchDoc	Size: B
Engineer: Kevin Allen		Contact: http://www.ti.com/support	

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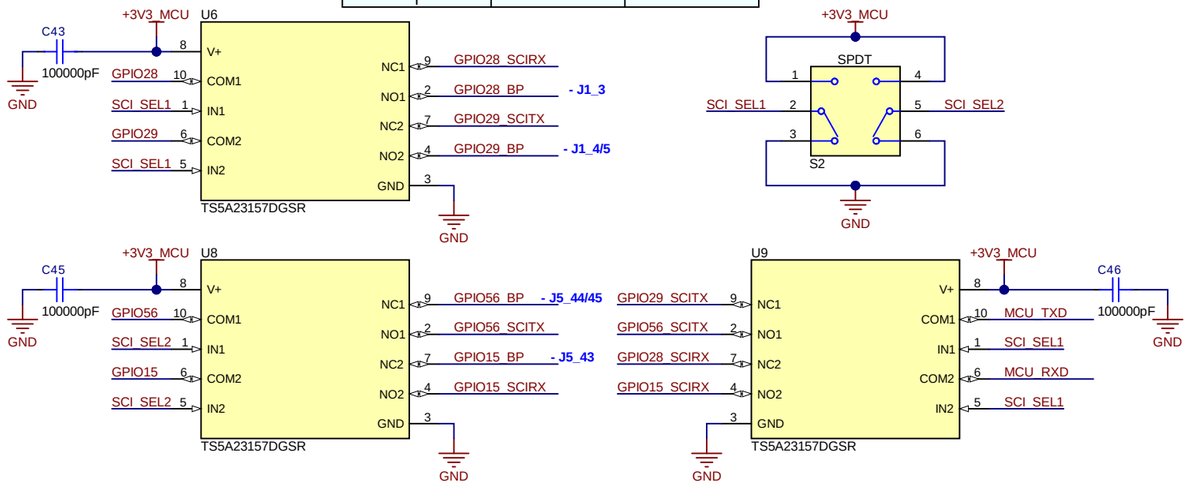
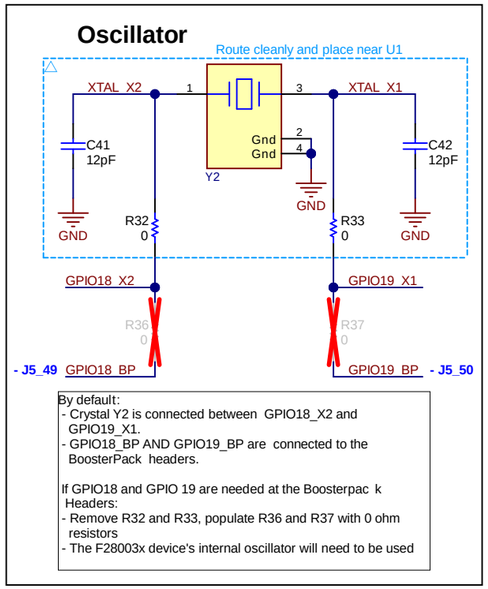
UART Routing

SCI_SEL1	SCI_SEL2	GPIO28/29 Route	GPIO15/56 Route
0	0	XDS110 COM Port	BP
0	1	XDS110 COM Port	NC
1	0	BP	BP
1	1	BP	XDS110 COM Port

- DEFAULT



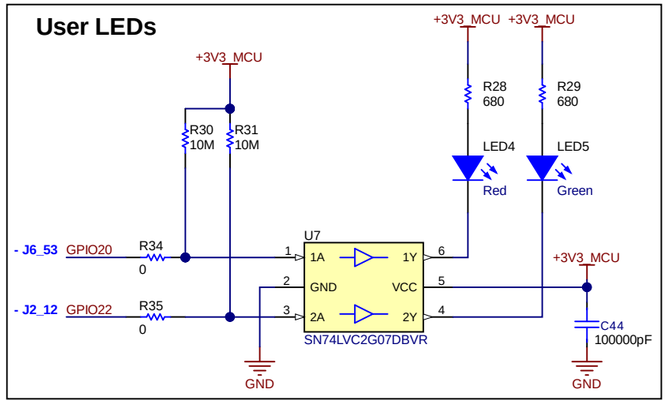
Oscillator



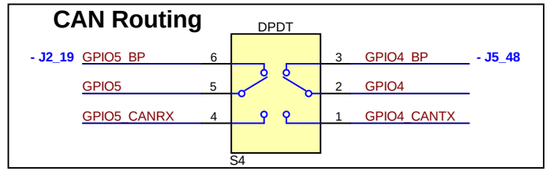
By default:
- Crystal Y2 is connected between GPIO18_X2 and GPIO19_X1.
- GPIO18_BP AND GPIO19_BP are connected to the BoosterPack headers.

If GPIO18 and GPIO 19 are needed at the Boosterpac k Headers:
- Remove R32 and R33, populate R36 and R37 with 0 ohm resistors
- The F28003x device's internal oscillator will need to be used

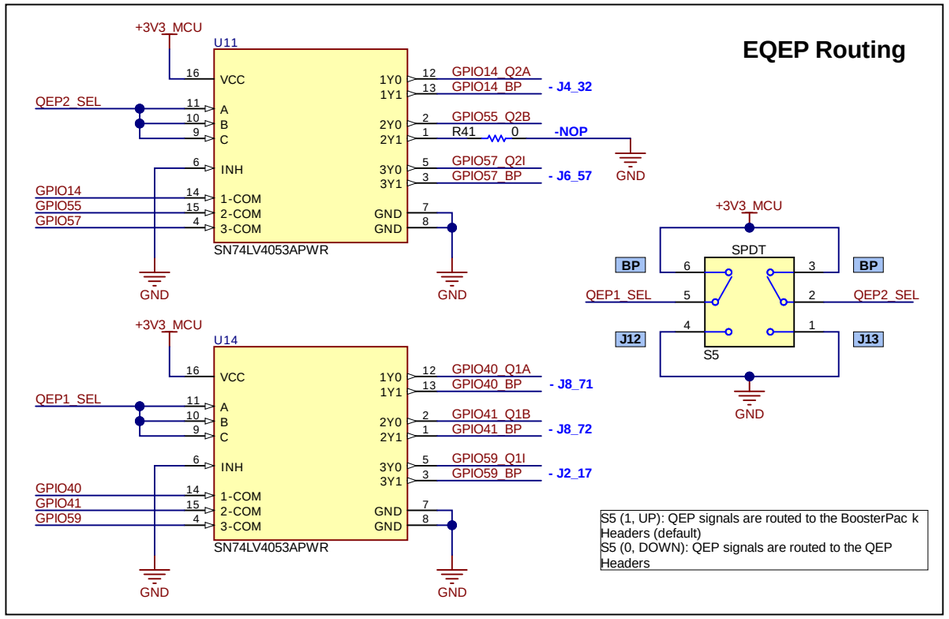
User LEDs



CAN Routing

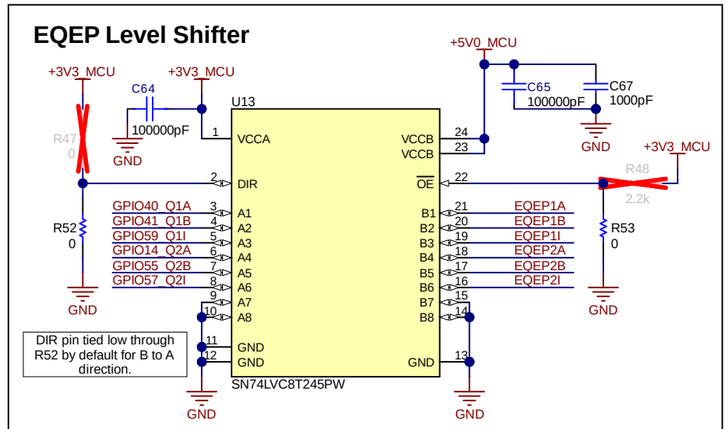


EQEP Routing



S5 (1, UP): QEP signals are routed to the BoosterPac k Headers (default)
S5 (0, DOWN): QEP signals are routed to the QEP Headers

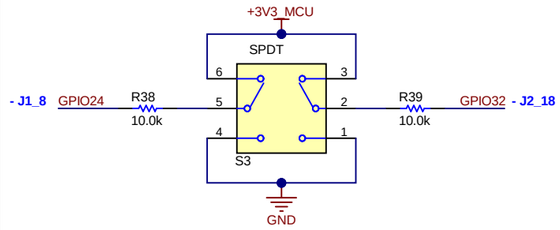
EQEP Level Shifter



DIR pin tied low through R52 by default for B to A direction.

To disable the Level Shifter:
1. De-populate R53
2. Place a 2.2k ohm resistor on R48 to pull-up OE

Boot Mode Select



Selected Boot Mode Chart

Mode #	GPIO24	GPIO32	Boot Mode
00	0	0	Boot from Parallel GPIO
01	0	1	Boot from SCI / Wait Mode
02	1	0	Boot from CAN
03	1	1	Boot from Flash

Orderable: LAUNCHXL-F280039C		Designed for: Public Release	Mod. Date: 12/9/2021
TID #: N/A		Project Title: LAUNCHXL-F280039C	
Number: MCU103	Rev: A	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 3 of 8
Drawn By:		File: MCU103A_AltRouting_Misc.SchDoc	Size: B
Engineer: Kevin Allen		Contact: http://www.ti.com/support	

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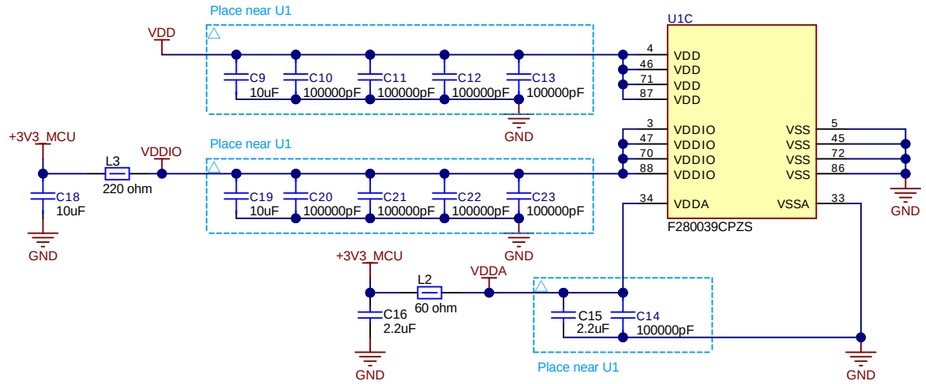
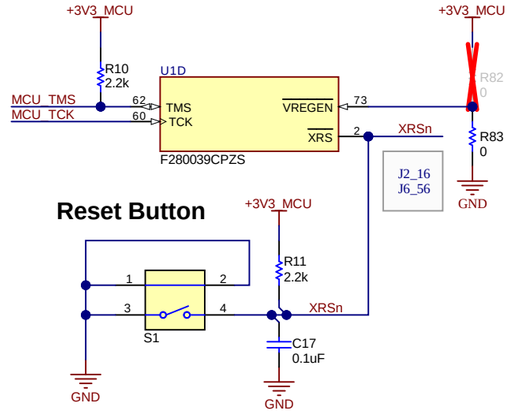
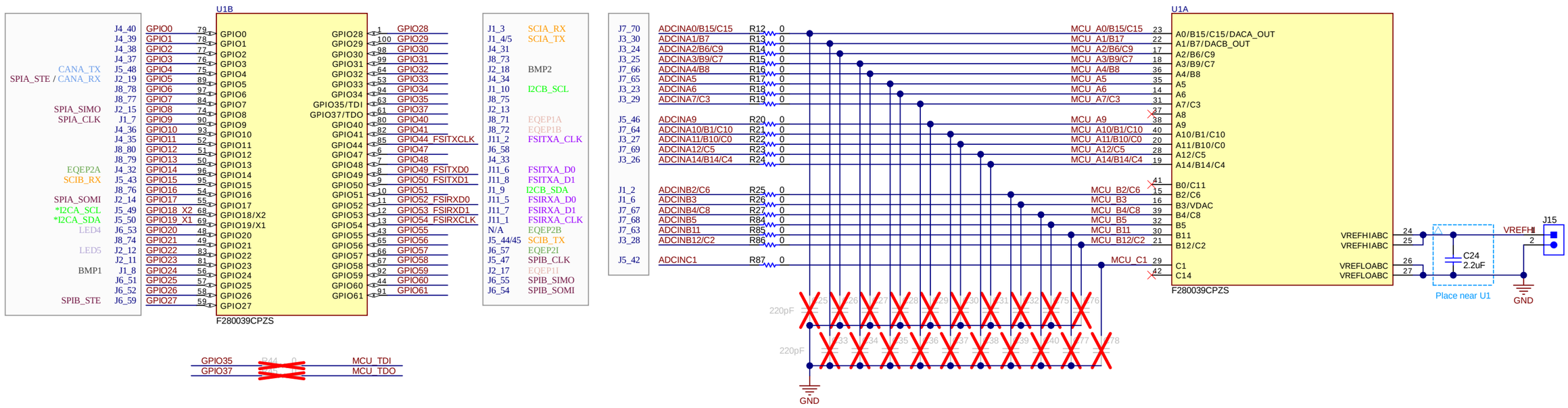
F28003x Device

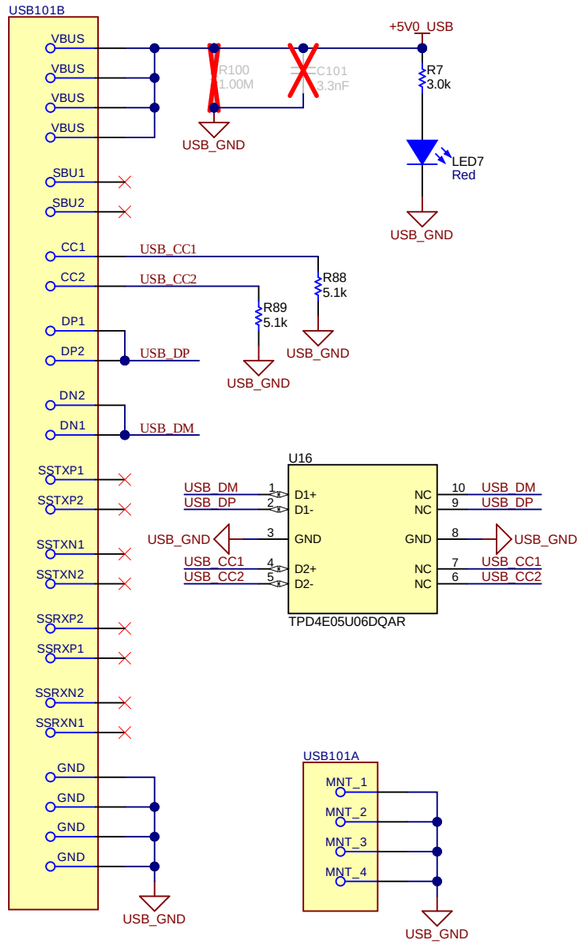




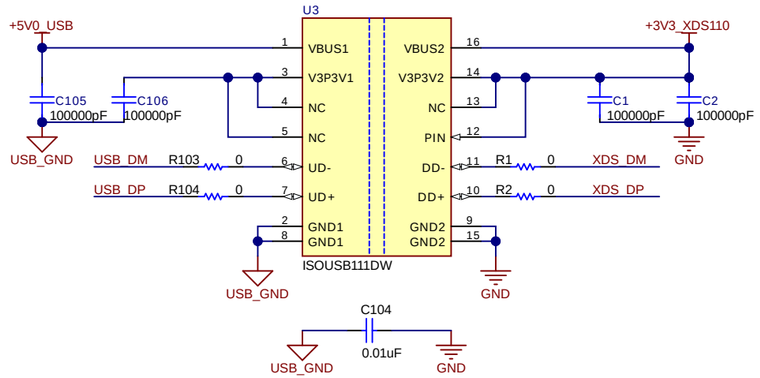


Orderable: LAUNCHXL-F280039C	Designed for: Public Release	Mod. Date: 12/9/2021	
TID #: N/A	Project Title: LAUNCHXL-F280039C		
Number: MCU103 Rev: A	Sheet Title:		
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 4 of 8	
Drawn By:	File: MCU103A_F280039C_Device.SchDoc	Size: B	
Engineer: Kevin Allen	Contact: http://www.ti.com/support		

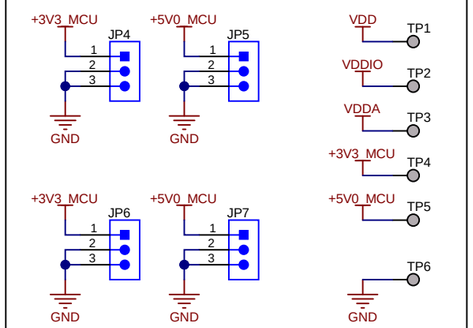
USB-C Connector



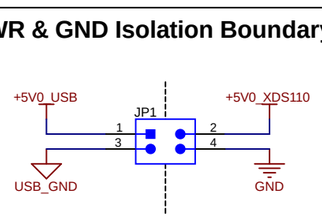
USB Isolation



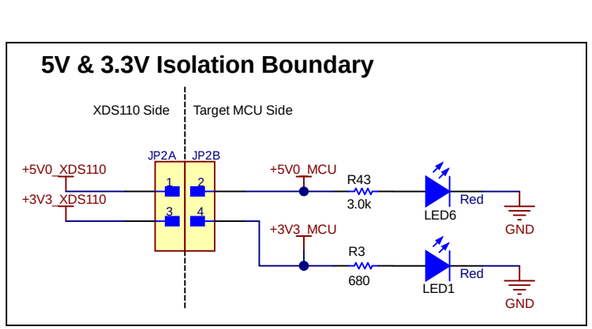
Power Headers and Test Points



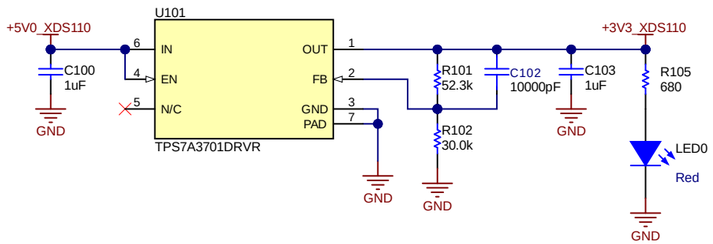
PWR & GND Isolation Boundary



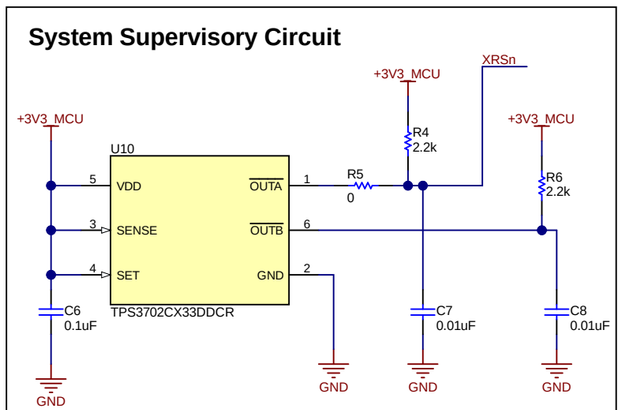
5V & 3.3V Isolation Boundary



5V to 3.3V



System Supervisory Circuit



Orderable: LAUNCHXL-F280039C		Designed for: Public Release	Mod. Date: 11/4/2021
TID #: N/A		Project Title: LAUNCHXL-F280039C	
Number: MCU103	Rev: A	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 6 of 8
Drawn By:		File: MCU103A_USB_and_Power.SchDoc	Size: B
Engineer: Kevin Allen		Contact: http://www.ti.com/support	

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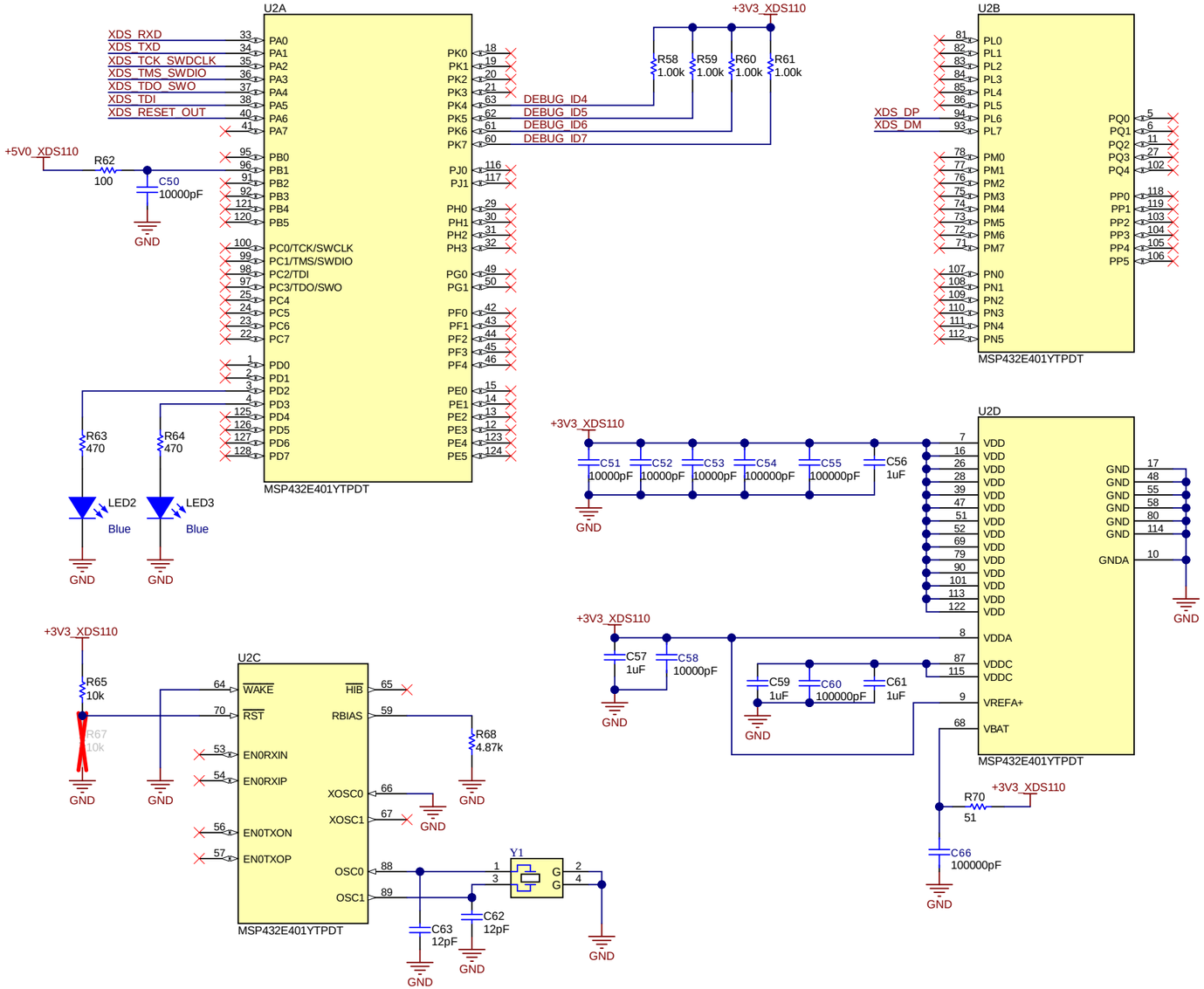
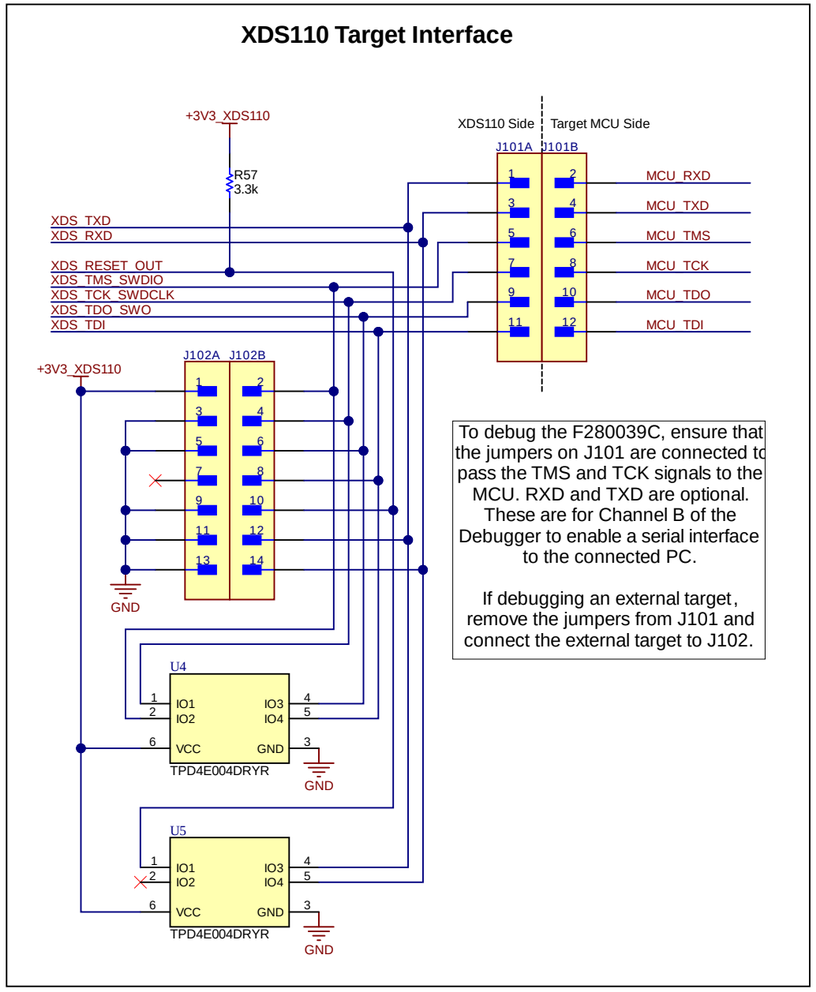
XDS110 Device



XDS110 Target Interface



Orderable: LAUNCHXL-F280039C		Designed for: Public Release	Mod. Date: 12/9/2021
TID #: N/A		Project Title: LAUNCHXL-F280039C	
Number: MCU103	Rev: A	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 7 of 8
Drawn By:		File: MCU103A_XDS110_MCU.SchDoc	Size: B
Engineer: Kevin Allen		Contact: http://www.ti.com/support	

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FID1 FID2 FID3 FID4 FID5 FID6

MH1 MH2 MH3 MH4

PCB Number: MCU103
PCB Rev: A

Logo1
PCB
LOGO
Texas Instruments

CE Logo1

Logo3
PCB
LOGO
FCC disclaimer

Logo4
PCB
LOGO
WEEE logo

Logo5
PCB
LOGO
Texas Instruments

M1 M2 M3 M4 M5 M6 M7 M8 M9 M10 M11 M12

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: LAUNCHXL-F280039C		Designed for: Public Release	Mod. Date: 8/26/2021
TID #: N/A		Project Title: LAUNCHXL-F280039C	
Number: MCU103	Rev: A	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 8 of 8
Drawn By:		File: MCU103A_Hardware.SchDoc	Size: B
Engineer: Kevin Allen		Contact: http://www.ti.com/support	

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